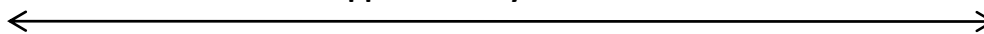


# RHA2116 Bare Die

Approximately 2.82 mm

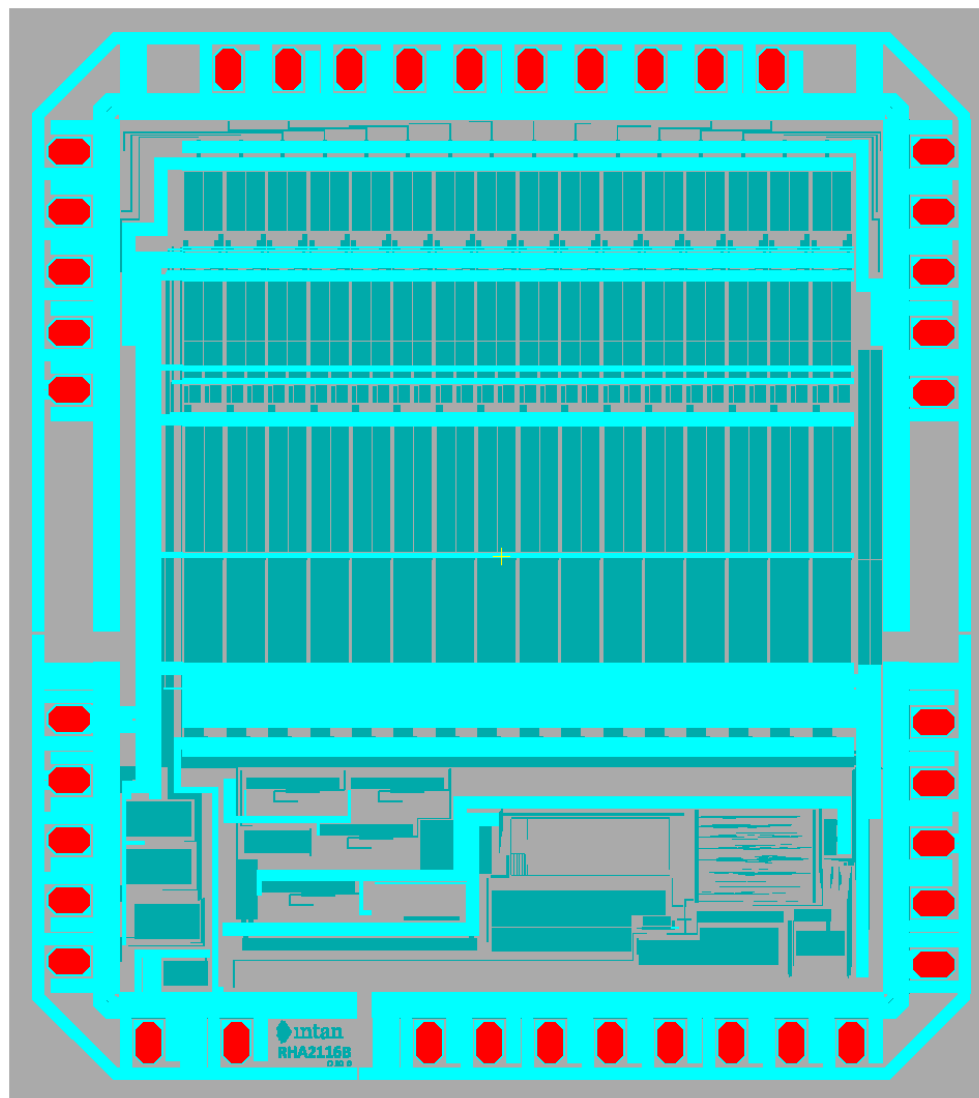


**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads



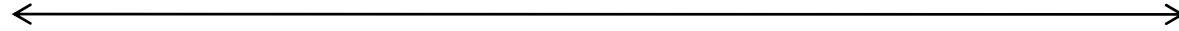
Approximately 3.14 mm

Each die is 254  $\mu\text{m}$  (10 mils) thick



# RHA2132 Bare Die

Approximately 4.82 mm

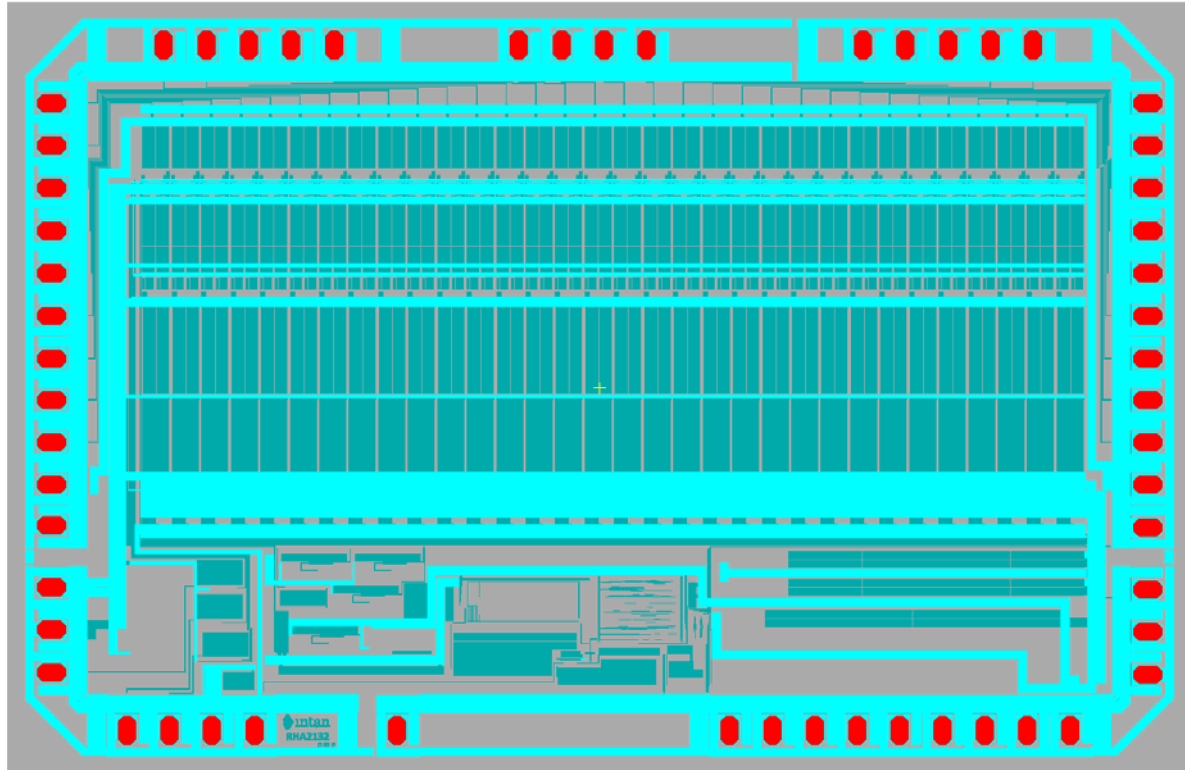


**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads



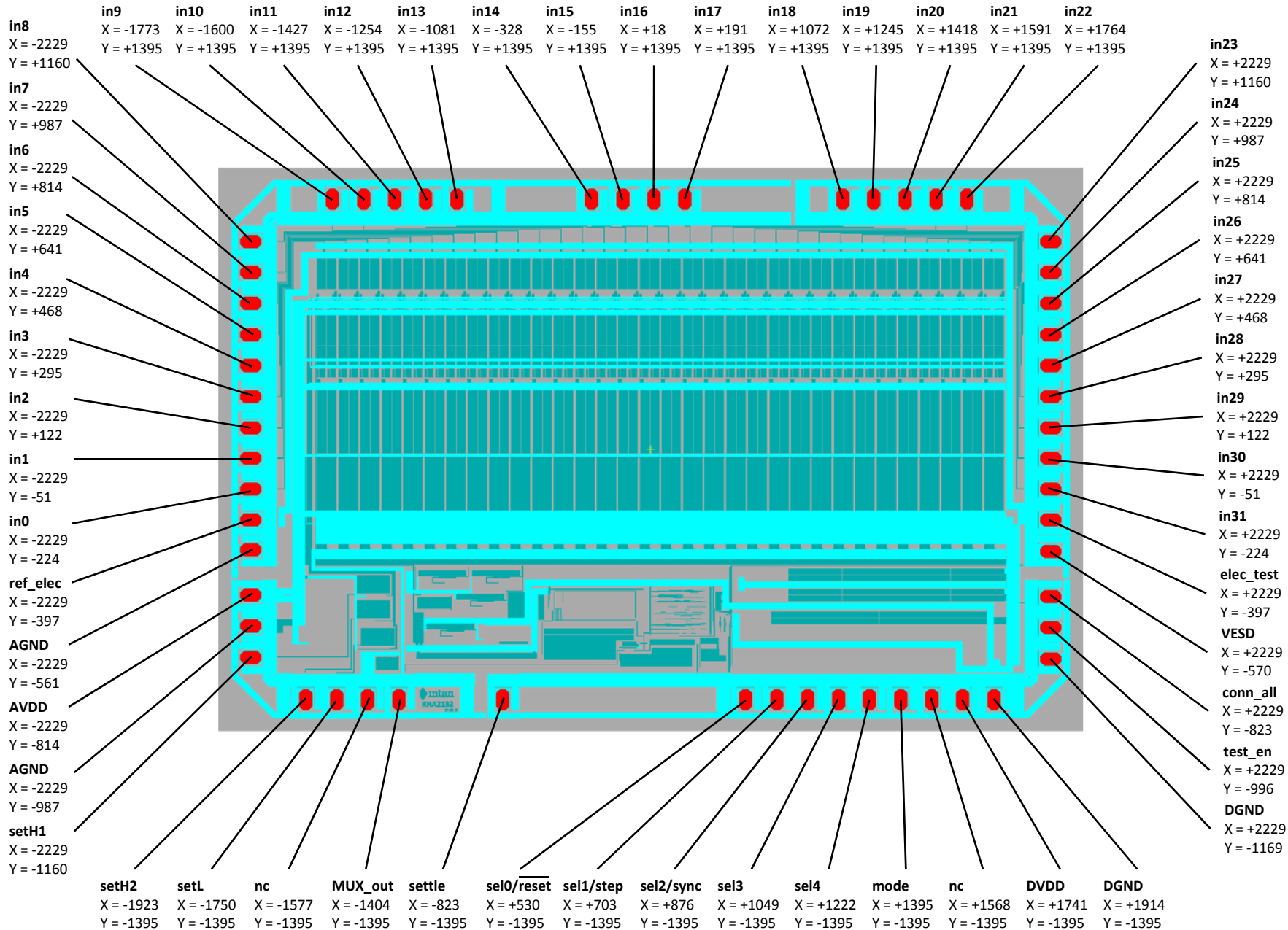
Approximately 3.14 mm

Each die is 254  $\mu\text{m}$  (10 mils) thick

# RHA2132

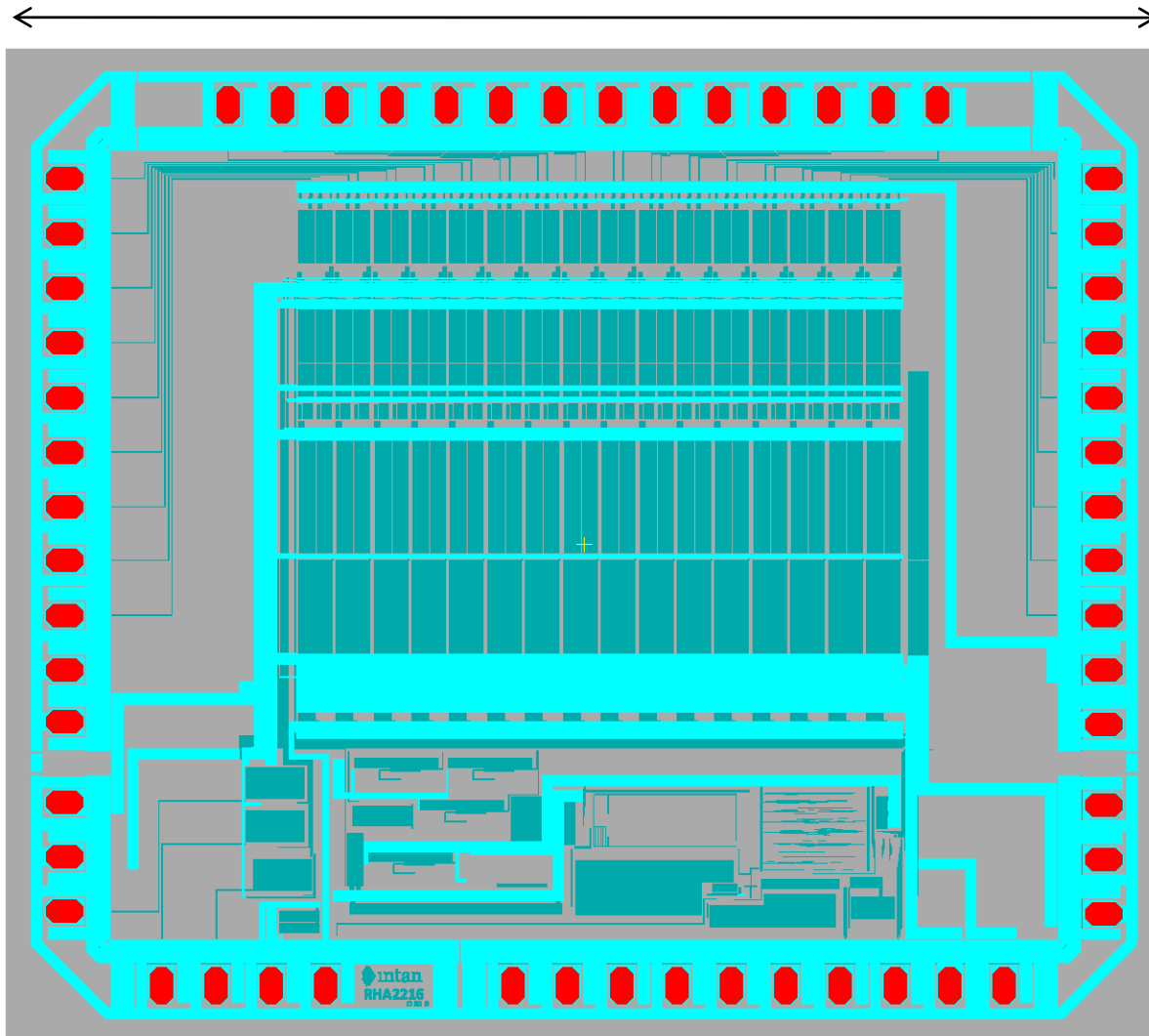
# Coordinates of Bondpad Centers, Relative to Center of Design

dimensions in microns



# RHA2216 Bare Die

Approximately 3.66 mm



**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads

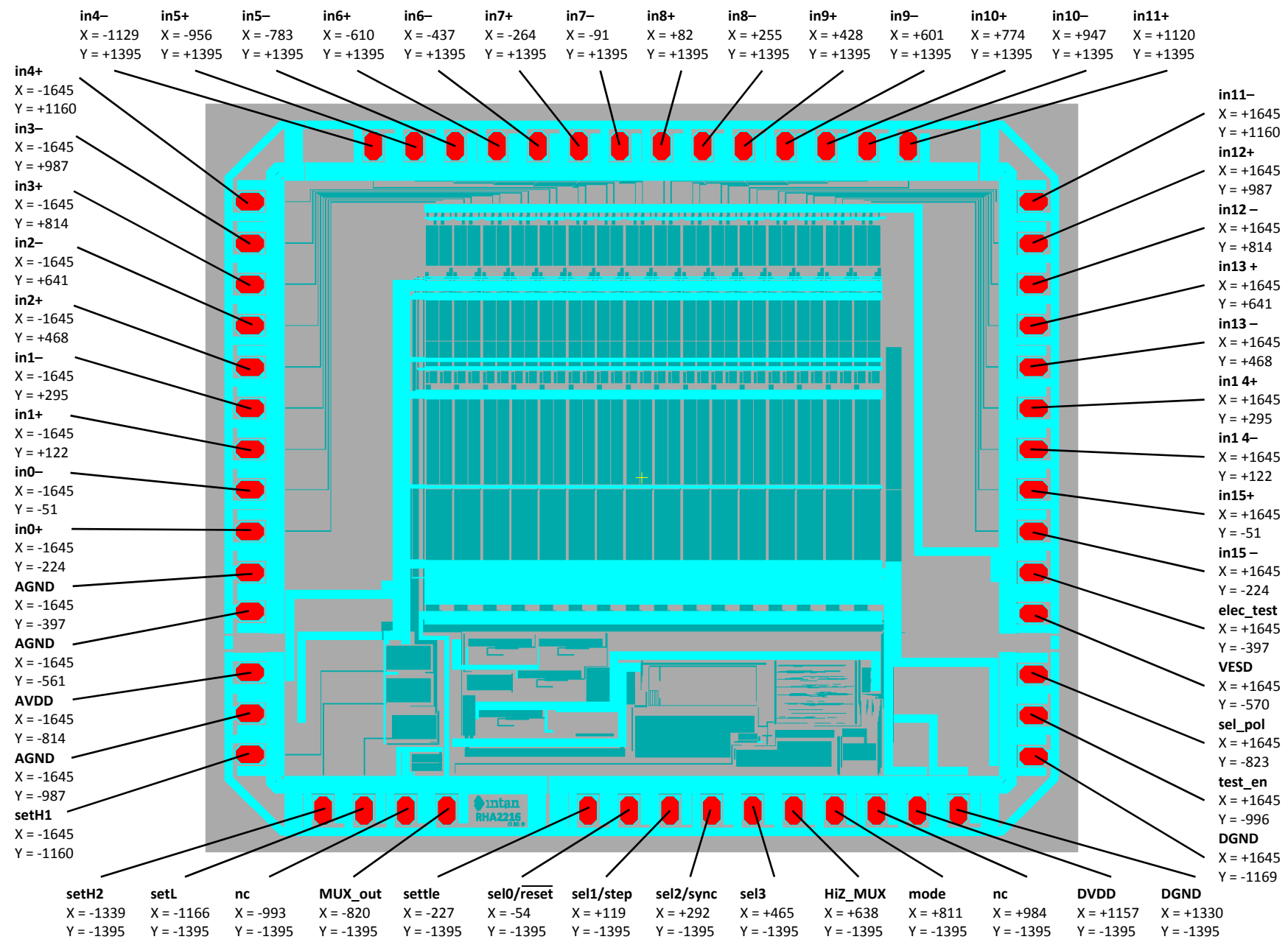
Approximately 3.14 mm

Each die is 254  $\mu\text{m}$  (10 mils) thick

# RHA2216

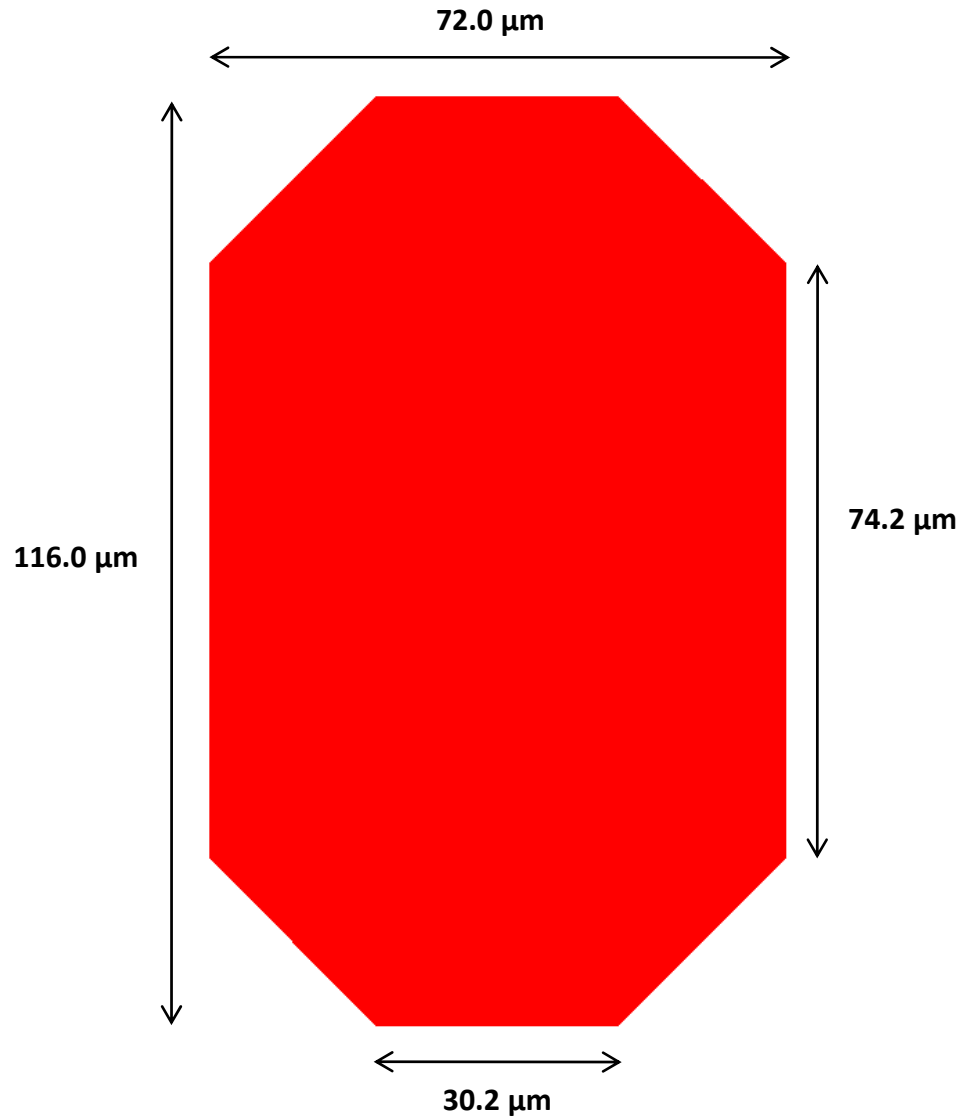
# Coordinates of Bondpad Centers, Relative to Center of Design

dimensions in microns



# RHA2000-Series Bondpad Dimensions

Bondpad metal: Aluminum



Minimum bond pad pitch (center to center) on RHA2000-series chips =  $173\ \mu\text{m}$